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3 Characteristic

Forward current	If	30	mA			
Reverse voltage	Vr	5	V			
Power dissipation	Pd	110	mW			
Operating temperature range	Top	-25 +80	C			
Storage temperature range	Tg	-30 +80	C			
Peak pulsing current 1/8 d f=1KH	Ifp	125	mA			
Wavelength at peak emission	If=20mA	peak	620	630	635	nm
			515	520	525	
Spectral half band width	If=20mA			10		
Forward voltage	If=20mA	Vf	1.8	2.0	2.4	V
			3.0	3.4	3.8	
Luminous intensity	If=20mA	I	500	650	800	mcd
			1000	1250	1500	
Viewing angle at 50% IV	If=10mA		--	120	--	Deg
Reverse current	Vr=5V	Ir	--	--	5	A



U ef I life

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IF=20mA

100000

H

Typical Electrical/Optical Characteristic Curve
(Ta=25 Unless Otherwise Noted)

If(mA)

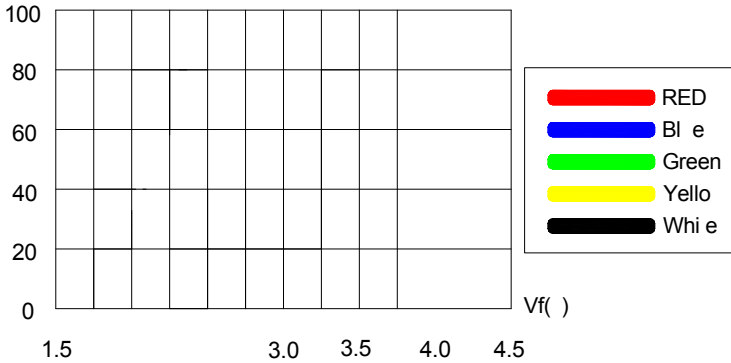


Fig.1 Forward Current vs Forward Voltage

IV

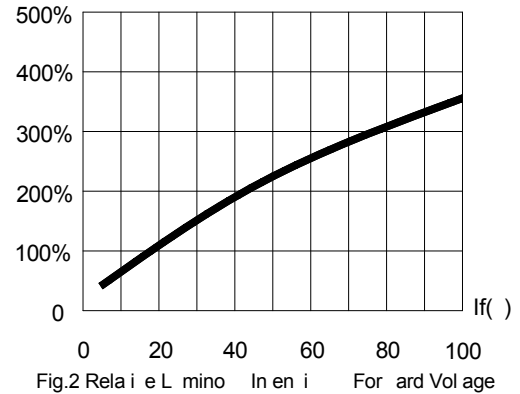


Fig.2 Relative Luminous Intensity vs Forward Voltage

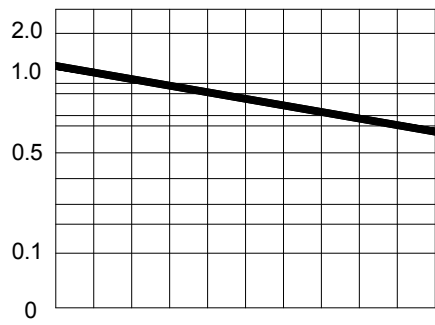


Fig.3 Relative Luminous Intensity vs Ambient Temperature

If(mA)

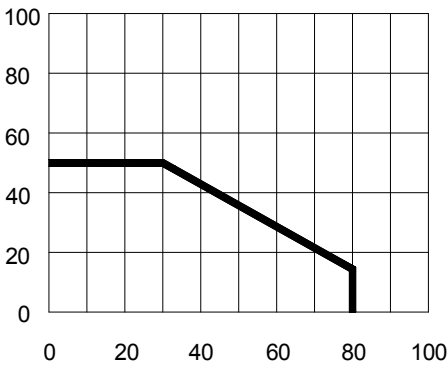


Fig.5 Maximum Forward Current vs Ambient Temperature

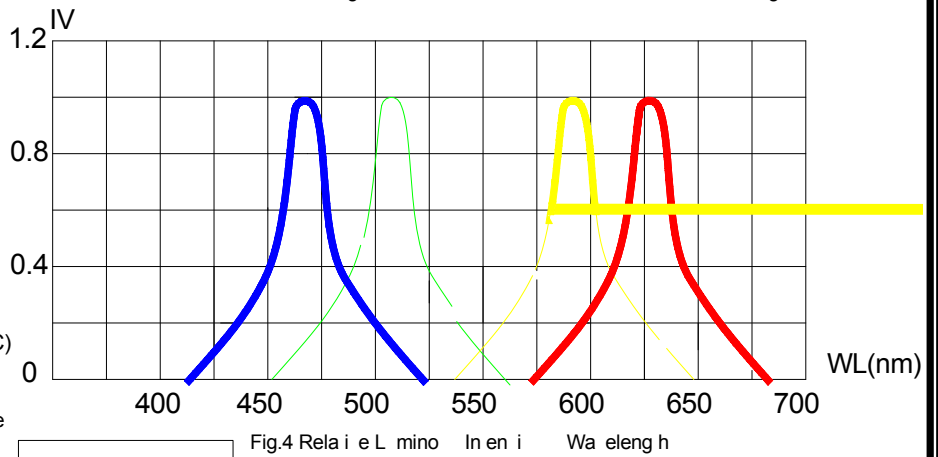
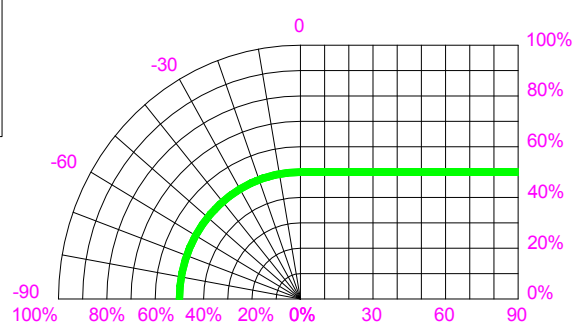


Fig.4 Relative Luminous Intensity vs Wavelength

Directional Characteristic





1	Tin-plated	Temp 260 ± 5	5 sec.	76 PCS	0/1
2	Back & forth under high & low temp alternately	High temp. +85 30min to 5min to -55 30min	50 bo	76 PCS	0/1
3	Heating	High temp. +100 30min To 10 sec to -10 30min	50 bo	76 PCS	0/1
4	High storage temp.	Temperature 100	1000 Hr.	76 PCS	0/1
5	Low storage temp.	-55	1000 Hr.	76 PCS	0/1
6	Life span	VF=1.9V IF=20mA	1000 Hr.	76 PCS	0/1
7	Test under high temp. & high humidity	85 ± 5/85%RH	1000 Hr.	76 PCS	0/1

i Iron Soldering: The Iron (max 30W) end temperature less than 300 °C, soldering time 3 seconds, soldering position is minimum 2mm from body.

ii Dip Soldering: Max temperature is 260 °C, time 5s, the position is minimum 2mm from body.

i Bracket must be bent only if 2mm from colloid.

ii Bracket mold must be finished before or professionally.

iii Bracket mold must be finished before soldering.

i Bracket mold holder should be connected between the pin, the distance gap of lead and the circuit board.

i. It should be paid attention to the ordering of all the devices in case of wrong polarity. Devices can be overlooked or the heat components, working condition can replace the limit.

ii. It should not assemble LED when the lead are deformed.

iii. When decide to assemble in hole, accurately according to the size of hole and hole distance of the line base

i. Suggesting good heating position

i. It should avoid any kind of quake or force on LED, before the soldering temperature returns normal.

It should be careful. When clean the body with chemical. Some chemical may bring damage to the surface, and bring color fading, such as, Trichloroethylene, Acetone. Should use ethanol or isopropyl, dip for no more than 3 minutes under the normal temperature.

